

REMARKS

New dependent claims 21 and 22 have been added to further scope the invention. No new matter has been entered.

The rejection of claims 1, 4-9, 16, 17 and 20 as obvious from Soga et al. (Soga) in view of Baba Mikio is in error.

The primary reference Soga does not show a stiffener surrounding a semiconductor chip, as the Examiner described in the Office Action. Moreover, there are other differences. More particularly, there is neither teaching nor suggestion anywhere in Soga that the second resin (outer portion of 11) is smaller in a thermal expansion coefficient than the first resin (portion of 11 under the chip) as required by Applicant's claims. Soga merely discloses that a thermal expansion coefficient of an epoxy resin is lowered by mixing an inorganic material, such as silica powder, in the epoxy resin. However, as shown in Figs. 6A to 6C in Soga, a coating resin is formed in one-step applying process. This results in that a mixing rate of the silica powder in a first resin (portion of 11 under the chip) equals a mixing rate of the silica powder in a second resin (outer portion of 11). In other words, in Soga, the mixing rate of the silica powder is uniform in a whole portion of a coating resin 11. Therefore, the thermal expansion coefficient of the second resin (outer portion of 11) is the same as the thermal expansion coefficient of the first resin (portion of 11 under the chip).

The secondary reference Baba Mikio merely discloses a semiconductor device having a stiffener 5 surrounding a semiconductor chip 2, and a silver paste 7 partially filling a space between the semiconductor chip 2 and stiffener 5. Baba Mikio cannot be said to teach that the second resin is smaller in a thermal expansion coefficient than the first resin, because Baba Mikio doesn't show a second resin. Even if the stiffener disclosed in Baba Mikio is

incorporated into the semiconductor device taught by Soga, no combination of Soga and Baba Mikio would achieve or suggest this feature of claim 1 or claim 7.

Claims 4-9, 16, 17 and 20 depend directly or indirectly on claim 1 or claim 7, as the case may be and are allowable over the Soga/Baba Mikio combination for the same reasons above adduced relative to claims 1 and 7 as well as for their own additional limitations.

New claims 21 and 22 are also allowable over the Soga/Baba Mikio combination for the same reasons above adduced relative to claims 1 and 7, as the case may be, as well as for their own additional limitations.

Having dealt with all the objections raised by the Examiner, the Application is believed to be in order for allowance. Early and favorable action is respectfully requested.

In the event there are any fee deficiencies or additional fees are payable, please charge them (or credit any overpayment) to our Deposit Account Number 08-1391.

Respectfully submitted,



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